

GM-1100

BTL-S/14/13/12th Gen Intel® Core™ Series Embedded GPU Computer,
Supports 1x MXM 3.1 GPU Expansion Socket

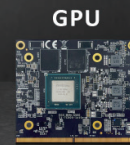


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PRODUCT
OF THE YEAR
Silver Award



THE RUGGED, COMPACT GPU COMPUTER

GM-1100: A Fusion of Power with NVIDIA MXM GPU and Intel® BTL-S/14/13/12th Gen CPU

Overview

CONTACT

The GM-1100 is a compact and rugged embedded MXM GPU computer for high-performance computing needs. It combines powerful computing and graphics processing capabilities with highly flexible expansion, making it ideal for edge AI applications with limited installation space.

Key Features

- Intel® BTL-S/14/13/12th Gen. Bartlett Lake-S / Raptor Lake-S Refresh / Raptor Lake-S / Alder Lake-S Platform (max 65 W TDP)
- Supports 1x MXM 3.1 Type A/B form factor GPU module expansion
- 1x 2.5GbE LAN, 1x 20Gbps USB3.2 Gen2 x2, Type C Connector
- 1x M.2 Key M Type 2280 Socket For Storage/Add-on Card Expansion
- 1x M.2 Key E Type 2230 Socket For Wireless/Bluetooth/Storage/Intel CNVi Module Expansion
- 1x M.2 Key B Type 3042/3052 Socket For 5G/GNSS/Storage/Add-on Card Expansion
- 2x M.2 Key B Type 2242 Socket For GNSS/Storage/Add-on Card Expansion
- Optional CMI & CFM Modules for I/O Expansion & Power Ignition Sensing Function
- Wide operating temperature -40°C to 70°C (-40°F - 158°F)

Certifications



MIL-STD-810H



EN 50121-3-2



EN 62368-1



EN 45545



UL LISTED



E13

3X Performance boost

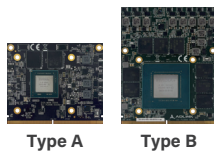
Equipped with a 14th generation Intel® Core (Raptor Lake-S Refresh) processor, the GM-1100 is capable of three times the computing performance of its predecessor. For highly complex or specialized tasks the hybrid or P-core monolithic architecture can be chosen for the best performance based on specific needs.

14th Intel® Raptor Lake-S Refresh



MXM GPU module

Type A and B MXM GPU modules allow comprehensive options to suit lightweight AI or high-performance AI inference applications. The special modular design also means painless upgrades to higher-end MXM modules to bolster performance in the future.



High-speed connections and data storage

Native 2.5GbE LAN and 20Gbps USB 3.2 Gen2x2 Type-C high-speed connections effectively improve the efficiency of image and file transfer. Storage options include two 2.5" HDD/SSD bays and options for high-speed NVMe SSD storage.





Ideal for mobility applications

Compact size (260 x 200 x 85 mm), multiple M.2 expansion slots for 5G or Wi-Fi communication modules, and compliance with rail transit certification (EN50121-3-2) and vehicle certification (E-mark) make the GM-1100 ideal for mobility applications.



Superior cooling performance

The innovative thermal design improves system cooling by providing independent heat dissipation channels for the CPU and GPU to the upper cover and sides of the extruded aluminum case. Combined with an external fan, it provides a solid foundation for stable and reliable operation.



External fan
accelerates heat dissipation



Independent cooling
for CPU & GPU



Rugged safety

The harsh challenges of the Edge AI environment are overcome with industrial grade wide temperature (-40 to 70°C / -40 to 158°F) and wide voltage (9 to 48 VDC) support, and passing the US military shock standard (MIL-STD-810H) to ensure product stability and safety.



Specifications

Model Name	GM-1100
System	
Processor	▪ Bartlett Lake-S Intel® Core Series 2 P-Core Only CPU - Intel Core™ Processor 9 273PE 12 Cores Up to 5.7 GHz, TDP 65 W - Intel Core™ Processor 9 273PTE 12 Cores Up to 5.5 GHz, TDP 45 W - Intel Core™ Processor 7 253PE 10 Cores Up to 5.5 GHz, TDP 65 W - Intel Core™ Processor 7 253PTE 10 Cores Up to 5.4 GHz, TDP 45 W - Intel Core™ Processor 5 223PE 8 Cores Up to 5.4 GHz, TDP 65 W - Intel Core™ Processor 5 223PTE 8 Cores Up to 5.4 GHz, TDP 45 W - Intel Core™ Processor 5 213PE 8 Cores Up to 5.2 GHz, TDP 65 W - Intel Core™ Processor 5 213PTE 8 Cores Up to 5.2 GHz, TDP 45 W ▪ Bartlett Lake-S Intel® Core Series 2 Hybrid CPU - Intel Core™ Processor 7 251E 24 Cores Up to 5.6 GHz, TDP 65 W - Intel Core™ Processor 7 251TE 24 Cores Up to 5.4 GHz, TDP 45 W - Intel Core™ Processor 5 221E 14 Cores Up to 5.2 GHz, TDP 65 W - Intel Core™ Processor 5 221TE 14 Cores Up to 5.0 GHz, TDP 45 W - Intel Core™ Processor 5 211E 10 Cores Up to 4.9 GHz, TDP 65 W - Intel Core™ Processor 5 211TE 10 Cores Up to 4.8 GHz, TDP 45 W - Intel Core™ Processor 3 201E 4 Cores Up to 4.8 GHz, TDP 60 W - Intel Core™ Processor 3 201TE 4 Cores Up to 4.6 GHz, TDP 45 W ▪ 14th Generation Intel® Raptor Lake-S Refresh Series P-Core Only CPU: - Intel® Core™ i9-14901E 8 Cores Up to 5.6 GHz, TDP 65W - Intel® Core™ i7-14701E 8 Cores Up to 5.4 GHz, TDP 65W - Intel® Core™ i5-14501E 6 Cores Up to 5.2 GHz, TDP 65W - Intel® Core™ i5-14401E 6 Cores Up to 4.7 GHz, TDP 65W - Intel® Core™ i3-14100 4 Cores Up to 4.7 GHz, TDP 60W - Intel® Core™ i9-14901TE 8 Cores Up to 5.5 GHz, TDP 45W - Intel® Core™ i7-14701TE 8 Cores Up to 5.2 GHz, TDP 45W - Intel® Core™ i5-14501TE 6 Cores Up to 5.1 GHz, TDP 45W - Intel® Core™ i5-14401TE 6 Cores Up to 4.5 GHz, TDP 45W - Intel® Core™ i3-14100T 4 Cores Up to 4.4 GHz, TDP 35W - Intel® Processor 300 2 Cores Up to 3.9 GHz, TDP 46W - Intel® Processor 300T 2 Cores Up to 3.4 GHz, TDP 35W ▪ 14th Generation Intel® Raptor Lake-S Refresh Series Hybrid CPU: - Intel® Core™ i9-14900 24 Cores Up to 5.8 GHz, TDP 65W - Intel® Core™ i7-14700 20 Cores Up to 5.4 GHz, TDP 65W - Intel® Core™ i5-14500 14 Cores Up to 5.0 GHz, TDP 65W - Intel® Core™ i5-14400 10 Cores Up to 4.7 GHz, TDP 65W - Intel® Core™ i9-14900T 24 Cores Up to 5.5 GHz, TDP 35W - Intel® Core™ i7-14700T 20 Cores Up to 5.2 GHz, TDP 35W - Intel® Core™ i5-14500T 14 Cores Up to 4.8 GHz, TDP 35W - Intel® Core™ i5-14400T 10 Cores Up to 4.5 GHz, TDP 35W ▪ 13th Generation Intel® Raptor Lake-S Series P-Core Only CPU: - Intel® Core™ i3-13100E 4 Cores Up to 4.4 GHz, TDP 60W - Intel® Core™ i3-13100TE 4 Cores Up to 4.1 GHz, TDP 35W ▪ 13th Generation Intel® Raptor Lake-S Series Hybrid CPU: - Intel® Core™ i9-13900E 24 Cores Up to 5.2 GHz, TDP 65W - Intel® Core™ i7-13700E 16 Cores Up to 5.1 GHz, TDP 65W - Intel® Core™ i5-13500E 14 Cores Up to 4.6 GHz, TDP 65W - Intel® Core™ i5-13400E 10 Cores Up to 4.6 GHz, TDP 65W - Intel® Core™ i9-13900TE 24 Cores Up to 5.0 GHz, TDP 35W - Intel® Core™ i7-13700TE 16 Cores Up to 4.8 GHz, TDP 35W - Intel® Core™ i5-13500TE 14 Cores Up to 4.5 GHz, TDP 35W ▪ 12th Generation Intel® Alder Lake-S Series P-Core Only CPU: - Intel® Pentium® G7400E 2 Cores Up to 3.6 GHz, TDP 46W - Intel® Pentium® G7400TE 2 Cores Up to 3.0 GHz, TDP 35W - Intel® Celeron® G6900E 2 Cores Up to 3.0 GHz, TDP 46W - Intel® Celeron® G6900TE 2 Cores Up to 2.4 GHz, TDP 35W ▪ 12th Generation Intel® Alder Lake-S Series Hybrid CPU: - Intel® Core™ i9-12900E 16 Cores Up to 5 GHz, TDP 65W - Intel® Core™ i7-12700E 12 Cores Up to 4.8 GHz, TDP 65W - Intel® Core™ i5-12500E 6 Cores Up to 4.5 GHz, TDP 65W - Intel® Core™ i3-12100E 4 Cores Up to 4.2 GHz, TDP 60W - Intel® Core™ i9-12900TE 16 Cores Up to 4.8 GHz, TDP 35W - Intel® Core™ i7-12700TE 12 Cores Up to 4.7 GHz, TDP 35W - Intel® Core™ i5-12500TE 6 Cores Up to 4.3 GHz, TDP 35W - Intel® Core™ i3-12100TE 4 Cores Up to 4.0 GHz, TDP 35W

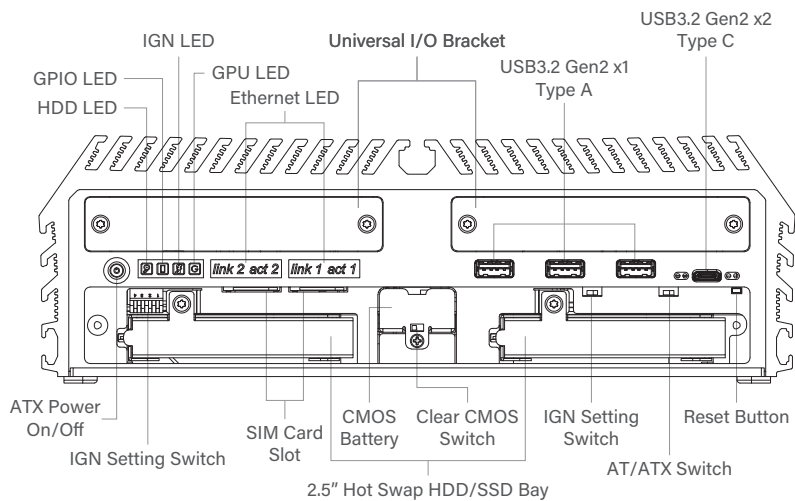
System	
Chipset	Intel R680E Chipset
Memory	2x DDR5 SO-DIMM sockets, support Un-buffered and ECC Type memory, up to 96GB. - Core™ i9/i7: Support 5600/4800 MHz with Single Rank memory and 5200/4800 MHz with Dual Rank memory. - Core™ i5/i3/Pentium®/Celeron®/Intel® Processor: Support 4800 MHz.
BIOS	AMI BIOS
Graphics	
Graphics Engine	- Integrated Intel® UHD Graphics 770: Core™ i9/i7/i5 - Integrated Intel® UHD Graphics 730: Core™ i3 - Integrated Intel® UHD Graphics 710: Pentium®/Celeron®
Maximum Display Output	Supports Triple Independent Display
DP	1x DisplayPort Connector (4096 x 2304@60Hz) *Verified maximum resolution: 3840 x 2160@60Hz
HDMI	1x HDMI Connector (4096 x 2160@30Hz) *Verified maximum resolution: 3840 x 2160@30Hz
VGA	1x VGA Connector (1920 x 1200 @60Hz)
Audio	
Audio Codec	Realtek® ALC888, High Definition Audio
Line-out	1x Line-out, Phone Jack 3.5mm
Mic-in	1x Mic-in, Phone Jack 3.5mm
I/O	
LAN	1x 2.5GbE LAN, RJ45 - Intel® I225 1x 1GbE LAN, RJ45 - Intel® I219
COM	4x RS-232/422/485 with Auto Flow Control (Supports 5V/12V), DB9
USB	1x 20Gbps USB3.2 Gen2 x2, Type C 3x 10Gbps USB3.2 Gen2 x1, Type A 4x 5Gbps USB3.2 Gen1 x1, Type A
Storage / Expansion	
2.5" SSD/HDD	2x 2.5" Front Accessible SATA HDD/SSD Bay Supporting Hot Swap Function (SATA 3.0) (Up to 15mm in Height)
M.2 M Key Socket	1x M.2 Key M Type 2280 Socket (PCIe Gen 4x4 / SATA), Support Storage/Add-on Card Expansion
M.2 E Key Socket	1x M.2 Key E Type 2230 Socket (PCIe Gen 3x2 / USB2.0), Support Wireless/Bluetooth/Storage/Intel CNVi Module Expansion
M.2 B Key Socket	1x M.2 Key B Type 3042/3052 Socket (PCIe Gen 3x2 / USB3.2 Gen2x1 / SATA), Support 5G/GNSS/Storage/Add-on Card Expansion 2x M.2 Key B Type 2242 Socket (PCIe Gen 4x2 / USB2.0 / SATA), Support GNSS/Storage/Add-on Card Expansion
MXM Socket	1x MXM Carrier Board Socket for MXM GPU Module Expansion
SIM Socket	2x SIM Socket
CMI (Combined Multiple I/O) Interface	1x High Speed CMI Interface for optional CMI Module Expansion 1x Low Speed CMI Interface for optional CMI Module Expansion
CFM (Control Function Module) Interface	1x CFM IGN Interface for optional CFM-IGN Module Expansion

Other Function	
RAID	• Support RAID 0/1/5/10
External FAN Connector	• 2x External FAN Connector, 4-pin Terminal Block (Support Smart Fan by BIOS)
Power Ignition Sensing	• Support Power Ignition Sensing Function with Delay Time Management and Selectable 12V/24V (With Optional CFM Module)
Clear CMOS Switch	• 1x Clear CMOS Switch
Reset Button	• 1x Reset Button
Instant Reboot	• Support 0.2sec Instant Reboot Technology
Watchdog Timer	• Software Programmable Supports 256 Levels System Reset
Antenna Holes	• 2x Antenna Holes
Status LED Indicator	• HDD LED 、GPIO LED 、IGN LED 、GPU LED 、Ethernet LED
Power	
Power Button	• 1x ATX Power On/Off Button
Power Mode Switch	• 1x AT/ATX Mode Switch
Power Input	• 9-48 VDC, Single Power Source - Connector Type: 2x 3-pin Terminal Block, Each Terminal Block Current Limitation is 15A • Power input voltage from 9V to 23V must use dual power connectors, power input voltage from 24V to 48V can use single power connector
Remote Power On/Off	• 1x Remote Power On/Off, 2-pin Terminal Block
Max. Power Consumption	• 35W CPU: 187.51W • 65W CPU: 258.96W - Test conducted with CPU, 1x RAM, and 1x storage - 100% load during burn-in testing.
Inrush Current (Peak)	• 35W CPU: 5.467 A@24V • 65W CPU: 5.725 A@24V
Physical	
Dimension (W x D x H)	• 260 x 200 x 85 mm
Weight Information	• 4.73 kg
Mechanical Construction	• Extruded Aluminum with Heavy Duty Metal
Mounting	• Wall / Side / DIN-RAIL / VESA Mount
Physical Design	• Fanless Design • Cableless Design • Jumper-less Design • Unibody Design
Reliability & Protection	
Reverse Power Input Protection	• Yes
Over Voltage Protection	• Protection Range: 51~58V • Protection Type: shut down operating voltage, re-power on at the preset level to recover
Over Current Protection	• 30A
CMOS Battery Backup	• SuperCap Integrated for CMOS Battery Maintenance-free Operation
MTBF	• 313,541 Hours - Database: Telcordia SR-332 Issue3, Method 1, Case 3
Operating System	
Windows	• Windows®11, Windows®10
Linux	• Ubuntu Desktop 22.04 LTS

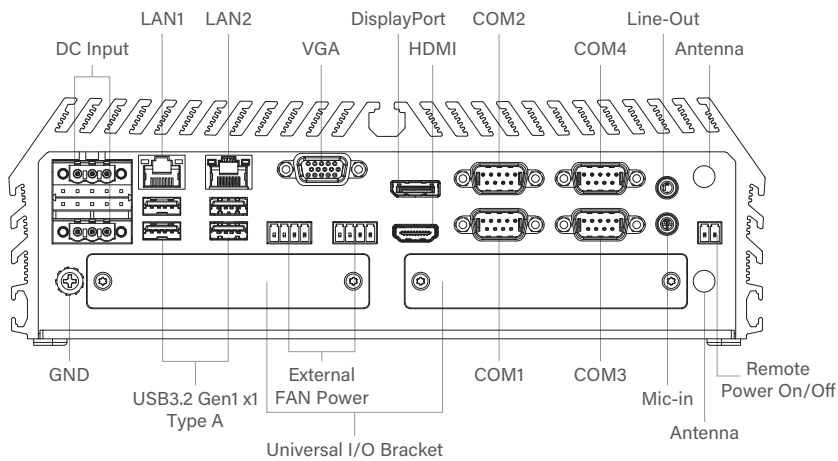
Environment	
Operating Temperature	• 35W TDP Processor: -40°C to 70°C (-40°F to 158°F) • 45W TDP Processor with external FAN: -40°C to 60°C (-40°F to 140°F) • 65W TDP Processor with external FAN: -40°C to 60°C (-40°F to 140°F) * PassMark BurnInTest: 100% CPU, 2D/3D Graphics (without thermal throttling) * For GM-1100 + MXM GPU Module operating temperature, please refer to the last page – Operating Temperature Matrix Table for more information * With extended temperature peripherals; Ambient with air flow * According to IEC60068-2-1, IEC60068-2-2, IEC60068-2-14
Storage Temperature	• -40°C to 70°C (-40°F to 158°F)
Relative Humidity	• 95%RH @ 70°C (non-Condensing)
Shock	• MIL-STD-810H
Vibration	• MIL-STD-810H
EMC	• CE, UKCA, FCC, ICES-003 Class A • EN 50155 (EN 50121-3-2 Only) • E-mark
EMI	• CISPR 32 Conducted & Radiated: Class A • EN/BS EN 50121-3-2 Conducted & Radiated: Class A • EN/BS EN IEC 61000-3-2 Harmonic current emissions: Class A • EN/BS EN 61000-3-3 Voltage fluctuations & flicker • FCC 47 CFR Part 15B, ICES-003 Conducted & Radiated: Class A
EMS	• EN/IEC 61000-4-2 ESD: Contact: 6 kV; Air: 8 kV • EN/IEC 61000-4-3 RS: 80 MHz to 1000 MHz: 20 V/m • EN/IEC 61000-4-4 EFT: AC Power: 2 kV; Signal: 2 kV • EN/IEC 61000-4-5 Surges: AC Power: 2 kV • EN/IEC 61000-4-6 CS: 10V (**Compliant with the standard when utilizing shielded cable.) • EN/IEC 61000-4-8 PFMF: 50 Hz, 1A/m • EN/IEC 61000-4-11 Voltage Dips & Voltage Interruptions: 0.5 cycles at 50 Hz
Fire Protection	• EN 45545-2
Safety	• UL, cUL , CB, IEC, EN 62368-1

External Layout

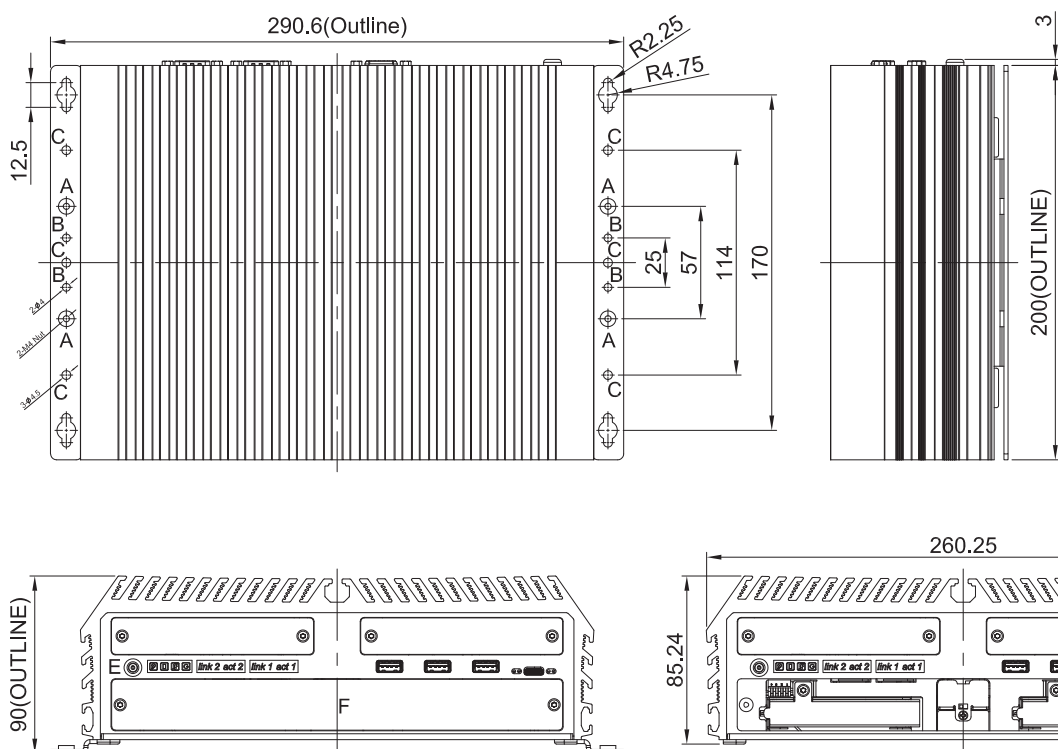
Front I/O



Rear I/O



Dimensions



Ordering Information

Available Models

Model No.	Description
GM-1100-R10	BTL-S/14/13/12th Gen Intel® Core™ Series Embedded GPU Computer, Supports 1x MXM 3.1 GPU Expansion Socket

Package Checklist

• GM-1100 GPU Computer x1	• Remote Function Terminal Block Connector x1
• CPU Heatsink Pack x1	• External Fan Terminal Block Connector x2
• Screw Pack x1	• Wall Mounting Kit x1
• Power Terminal Block Connector x2	• M.2 Key B Type 3052 to 3042 Adapter Bracket x1

Optional MXM GPU Module & Accessories

Model No.	Description
MXM-AD5000-R10	NVIDIA Embedded RTX AD5000 MXM Type B, 16G, 80W Kit with Heatsink and Thermal Pad
MXM-AD3500-R10	NVIDIA Embedded RTX AD3500 MXM Type B, 12G, 80W Kit with Heatsink and Thermal Pad
MXM-AD2000-R10	NVIDIA Embedded RTX AD2000 MXM Type A, 8G, 60W Kit with Heatsink and Thermal Pad
MXM-A4500-R10	NVIDIA Embedded RTX A4500 MXM Type B, 16G, 80W Kit with Heatsink and Thermal Pad
MXM-A2000-R10	NVIDIA Embedded RTX A2000 MXM Type A, 8G, 60W Kit with Heatsink and Thermal Pad
MXM-A1000-R10	NVIDIA Embedded RTX A1000 MXM Type A, 4G, 60W Kit with Heatsink and Thermal Pad
MXM-A500-R10	NVIDIA Embedded RTX A500 MXM Type A, 4G, 40W Kit with Heatsink and Thermal Pad
MXM-T1000-R10	NVIDIA Quadro Embedded T1000 MXM Kit with Heatsink and Thermal Pad
MXM-HSKA-01	MXM Type A Heatsink Kit for MXM-A500
MXM-HSKA-02	MXM Type A Heatsink Kit for MXM-A1000, MXM-A2000, and MXM-AD2000
MXM-HSKA-03	MXM Type A Heatsink Kit for MXM-T1000
MXM-HSKB-01	MXM Type B Heatsink Kit for MXM-A4500
MXM-HSKB-03	MXM Type B Heatsink Kit for MXM-AD3500 & MXM-AD5000

Optional Modules & Accessories

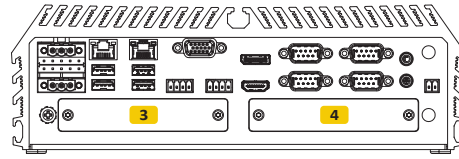
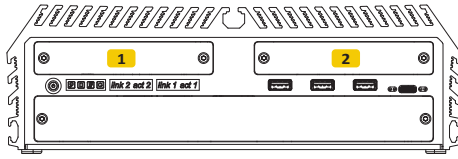
Model No.	Description
CB-DP02-R10	Carrier board with one MXM 3.1 interface and no DisplayPort output
CB-DP03-R10	Carrier Board with 1x MXM 3.1 Interface and 4x DisplayPort Output
CB-DP04-R10	Carrier Board with 1x MXM 3.1 Interface and 4x DisplayPort Output
CB-DP05-R10	Carrier Board with 1x MXM 3.1 Interface and 3x DisplayPort Output
CMI-LAN01-R12	CMI Module with 4x RJ45 Intel I210 GbE LAN Ports
CMI-M12LAN01-R12	CMI Module with M12 A-Coded Connector, 4x Intel I210 GbE LAN Ports
CMI-XM12LAN01-R10	CMI Module with M12 X-Coded Connector, 4x Intel I210 GbE LAN Ports

CMI-2P5GLAN01-R10	CMI Module with 4x Intel 2.5GbE LAN, RJ45 Port
CMI-10GLAN01-R10	CMI Module with 2x Intel® X550 10GbE LAN, RJ45 Port
CMI-10GXM12LAN01-R10	CMI Module with 2x Intel 10GbE LAN, M12 X-Coded Connector
CMI-CAN01-R10	CMI Module with 2x CAN FD Ports
CMI-DIO01	CMI Module with 16x Optical Isolated DIO (8 in/8 out)
CMI-COM01	CMI Module with 2x RS232/422/485 (Support 5V/12V)
CFM-PoE01	CFM Module with PoE Control Function, Individual Port 25.5W
CFM-IGN01	CFM Module with Power Ignition Sensing Control Function, 12V/24V Voltage Detection Selectable
MEC-COM-2032i	M.2 2242/2260/2280 (B+M key) 2-port RS-232/422/485 isolated serial board (-40°C~+85°C), 2x DB9 Connector
UB0932-R10	Universal Bracket with 3x Antenna Cutout
UB1303	Universal Bracket with 2x DB9 Cutout
UB1310	Universal Bracket with 4x M12 Cutout
UB1312	Universal Bracket with 4x RJ45 Cutout
UB1318	Universal Bracket with DIO Cutout
UB1328	Universal Bracket with 2x RJ45 Cutout
UB1329	Universal Bracket with 4x DP
UB1330-R10	Universal Bracket with 4x M12 X-Coded Cutout
UB1332-R10	Universal Bracket with 3x Antenna Cutout
UB1336-R10	Universal Bracket with 3x DP Cutout
UB1337-R10	Universal Bracket with 2x M12 X-coded Cutout
UB1338-R10	Universal Bracket with 2x DB9 and 1x Switch Cutout for CMI-CAN Expansion
FAN-EX102	External Fan Kit with 2x 4pin Terminal Block Plug for GM Series, Support Smart Fan Function
SIDE-GM	GM Series side mount kit
DIN01	DIN-RAIL Mount Kit, KMRH-K175
GST220A24-CIN	Adapter AC/DC 24V 9.2A 220W with 3pin Terminal Block Plug 5.0mm Pitch, with TUBES, level VI
GST360A24-CIN	Adapter AC/DC24V 15A 360W with 3pin Terminal Block Plug 5.0mm Pitch, with TUBES, level VI
RSD-200D-24	Railway Single Output DC-DC Converter 200W / DC 24V
Power Cable	1M Power Cable with 3-Pin Terminal Block Plug, Stripped and Tinned End with Tube

Carrier Board and MXM GPU Compatibility Matrix

	CB-DP02 (compatible with standard UB)	CB-DP03/UB1329	CB-DP04/UB1329	CB-DP05/UB1336
MXM-AD5000			V	
MXM-AD3500			V	
MXM-AD2000				V
MXM-A500	V			
MXM-A1000		V		
MXM-A2000		V		
MXM-A4500			V	
MXM-T1000		V		

Optional Module Configuration



Model No.	Description	1	2	3	4
CB-DP02-R10 	Carrier board with one MXM 3.1 interface and no DisplayPort output (Compatible with GM-1100 standard universal bracket)	V	-	-	-
CB-DP03-R10/UB1329 	Carrier Board with 1x MXM 3.1 Interface and 4x DisplayPort Output / 1x Universal Bracket with 4xDP Cutout	V	-	-	-
CB-DP04-R10/UB1329 	Carrier Board with 1x MXM 3.1 Interface and 4x DisplayPort Output / 1x Universal Bracket with 4xDP Cutout	V	-	-	-
CB-DP05-R10/UB1336-R10 	Carrier Board with 1x MXM 3.1 Interface and 3x DisplayPort Output / 1x Universal Bracket with 3x DP Cutout	V	-	-	-
CMI-LAN01-R12/UB1312 	CMI Module with 4x Intel® I210 GbE LAN, RJ45 Port / 1x Universal Bracket with 4x RJ45 Cutout for GM Series	-	V	-	-
CMI-2P5GLAN01-R10/UB1312 	CMI Module with 4x Intel 2.5GbE LAN, RJ45 Port / 1x Universal Bracket with 4x RJ45 Cutout for GM Series	-	V	-	-
CMI-10GLAN01-R10/UB1328 	CMI Module with 2x Intel® X550 10GbE LAN, RJ45 Port / 1x Universal Bracket with 2x RJ45 Cutout for GM Series	-	V	-	-
CMI-M12LAN01-R12/UB1310 	CMI Module with M12 Connector, 4x Intel® GbE LAN Ports / 1x Universal Bracket with 4x M12 Cutout for GM Series	-	V	-	-
CMI-XM12LAN01-R10/UB1330-R10 	CMI Module with M12 X-Coded Connector, 4x Intel I210 GbE LAN Ports / Universal Bracket with 4x M12 X-Coded Cutout	-	V	-	-
CMI-10GXM12LAN01-R10/UB1337-R10 	CMI Module with 2x Intel 10GbE LAN, M12 X-Coded Connector / Universal Bracket with 2x M12 X-coded Cutout	-	V	-	-
CMI-CAN01-R10/UB1338-R10 	CMI Module with 2x CAN FD Ports / Universal Bracket with 2x DB9 and 1x Switch Cutout for CMI-CAN Expansion	-	V	-	-
CMI-DIO01/UB1318 	CMI Module with 16DIO (8in 8out) / 1xUniversal Bracket with DIO Cutout for DX & GM Series	-	-	-	V
CMI-COM01/UB1303 	CMI Module with 2x RS232/422/485 (Support 5V/12V) / 1x Universal Bracket with 2x DB9 Cutout for DX & GM Series	-	-	-	V
MEC-COM-2032i/UB1303 	M.2 2242/2260/2280 (B+M key) 2-port RS-232/422/485 isolated serial board (-40°C~+85°C), 2x DB9 Connector/ 1x Universal Bracket with 2x DB9 Cutout for DX & GM Series	-	-	V	-
UB0932-R10 	Universal Bracket with 3x Antenna Cutout	-	-	V	V
UB1332-R10 	Universal Bracket with 3x Antenna Cutout	V	V	-	-

Operating Temperature Matrix Table

MXM GPU TDP	35W CPU	45W CPU	65W CPU
40W	UP to 50°C (122°F)	UP to 50°C (122°F)	UP to 50°C (122°F)
60W~80W	UP to 40°C (104°F)	UP to 40°C (104°F)	UP to 40°C (104°F)

- * External Fan Kit - FAN-EX102 is required for above configurations.
- * PassMark BurnInTest: 100% CPU, 2D Graphics (without thermal throttling)
- * Furmark: 1920x 1080, 8x MSAA (without thermal throttling)